

**Features**

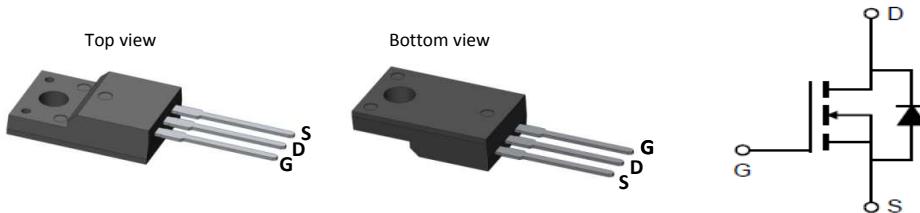
- CRM(CQ) Super\_Junction technology
- Much lower Ron\*A performance for On-state efficiency
- Better efficiency due to very low FOM

**Product Summary**

VDS	650V
R <sub>DS(on)</sub> _typ	0.32Ω
I <sub>D</sub>	11A

**Applications**

- LED/LCD/PDP TV and monitor Lighting
- Solar/Renewable/UPS-Micro Inverter System
- Charger
- Power Supply

**100% Avalanche Tested**

**Package Marking and Ordering Information**

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRJF380N65G2	-	TO-220F	Tube	N/A	N/A	50pcs

**Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Drain-source voltage	V <sub>DS</sub>	650	V
Continuous drain current T <sub>C</sub> = 25°C T <sub>C</sub> = 100°C	I <sub>D</sub>	11 7	A
Pulsed drain current (T <sub>C</sub> = 25°C, t <sub>p</sub> limited by T <sub>jmax</sub> )	I <sub>D</sub> pulse	44	A
Avalanche energy, single pulse (L=30mH, R <sub>g</sub> =30Ω)	E <sub>AS</sub>	75	mJ
Gate-Source voltage	V <sub>GS</sub>	±30	V
Power dissipation (T <sub>C</sub> = 25°C)	P <sub>tot</sub>	21	W
Operating junction and storage temperature	T <sub>j</sub> , T <sub>stg</sub>	-55...+150	°C

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Thermal resistance, junction – case. Max	R <sub>thJC</sub>	5.94	°C/W
Thermal resistance, junction – ambient. Max	R <sub>thJA</sub>	66	

**Electrical Characteristic (at T<sub>j</sub> = 25 °C, unless otherwise specified)**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

**Static Characteristic**

Drain-source breakdown voltage	BV <sub>DSS</sub>	650	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA
Gate threshold voltage	V <sub>GS(th)</sub>	3	-	4	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA
Zero gate voltage drain current	I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V T <sub>C</sub> =25°C T <sub>C</sub> =150°C
Gate-source leakage current	I <sub>GSS</sub>	-	0.5	100	nA	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V
Drain-source on-state resistance	R <sub>DS(on)</sub>	-	0.32	0.38	Ω	V <sub>GS</sub> =10V, I <sub>D</sub> =5.5A, T <sub>C</sub> =25°C T <sub>C</sub> =150°C
Transconductance	g <sub>fs</sub>	-	8.7	-	S	V <sub>DS</sub> =20V, I <sub>D</sub> =5.5A

**Dynamic Characteristic**

Input Capacitance	C <sub>iss</sub>	-	640	-	pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =100V, f=1MHz
Output Capacitance	C <sub>oss</sub>	-	32	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	0.3	-		
Gate Total Charge	Q <sub>G</sub>	-	19.8	-	nC	V <sub>GS</sub> =10V, V <sub>DS</sub> =480V, I <sub>D</sub> =5.5A
Gate-Source charge	Q <sub>gs</sub>	-	4.4	-		
Gate-Drain charge	Q <sub>gd</sub>	-	8.5	-		
Turn-on delay time	t <sub>d(on)</sub>	-	23	-	ns	T <sub>j</sub> =25°C, V <sub>GS</sub> =10V, I <sub>D</sub> =5.5A, V <sub>DS</sub> =400V, R <sub>g</sub> =27Ω
Rise time	t <sub>r</sub>	-	18	-		
Turn-off delay time	t <sub>d(off)</sub>	-	90	-		
Fall time	t <sub>f</sub>	-	15	-		
Gate resistance	R <sub>gint</sub>	-	6.7	-	Ω	f=1MHz



华润微电子(重庆)有限公司

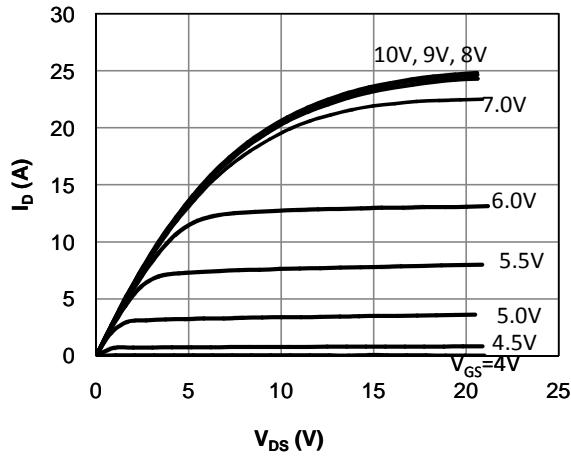
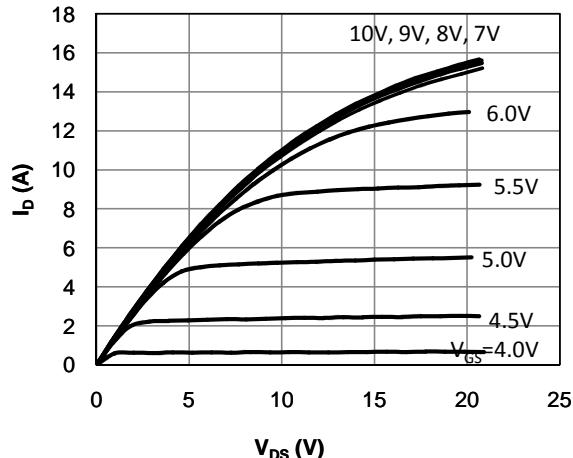
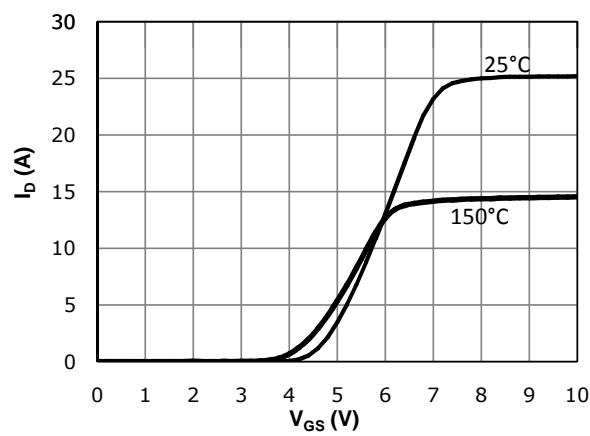
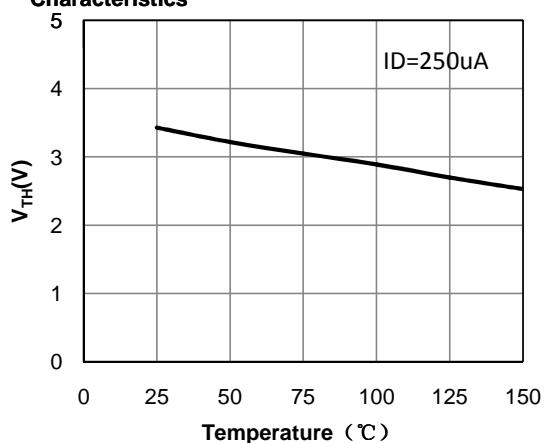
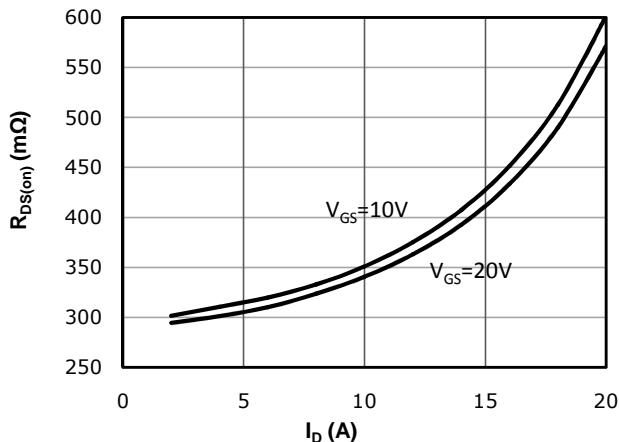
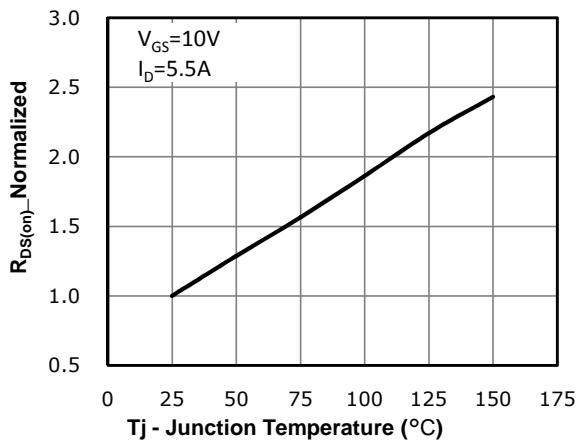
CRJF380N65G2

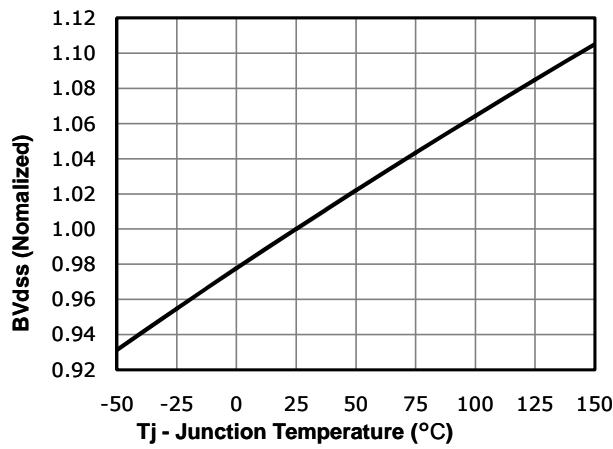
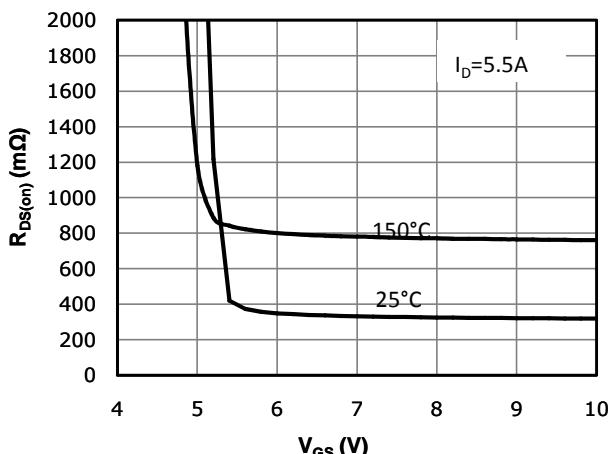
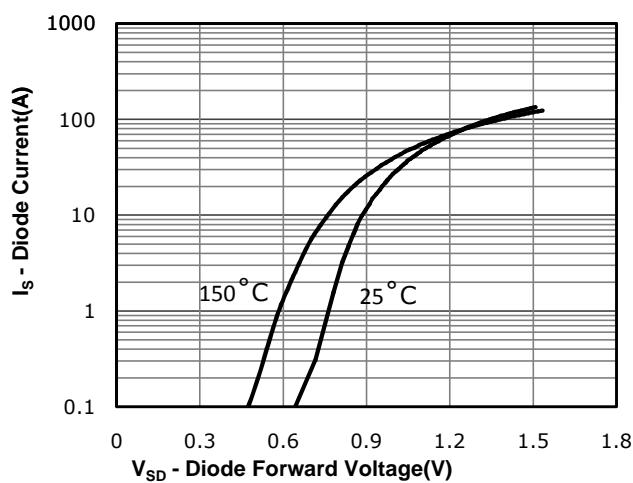
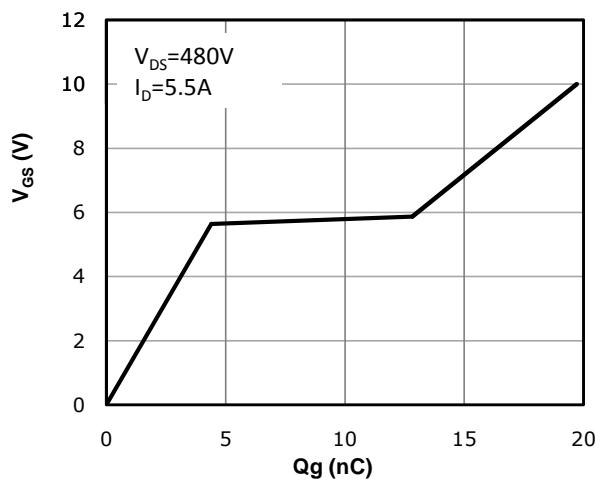
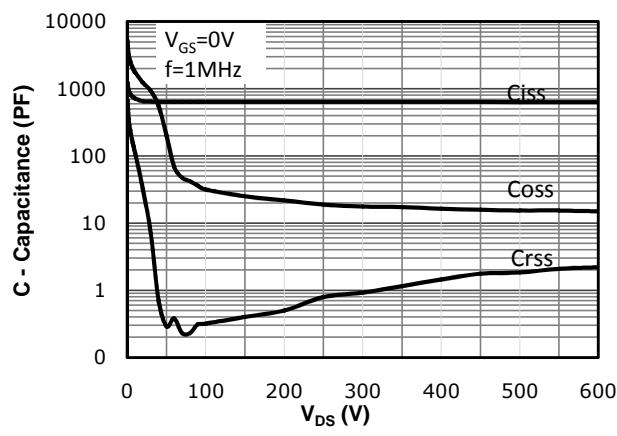
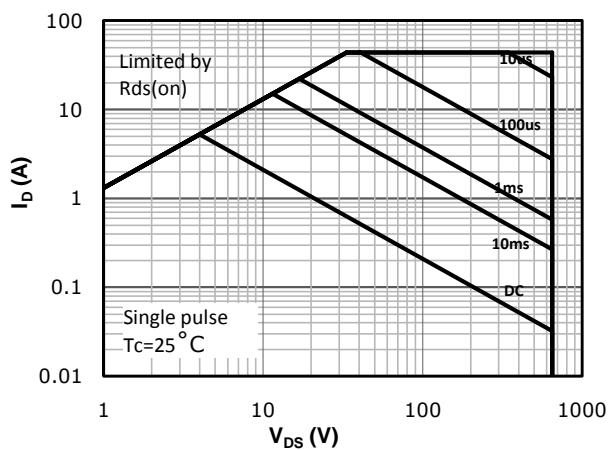
SJMOS N-MOSFET 650V, 0.32Ω, 11A

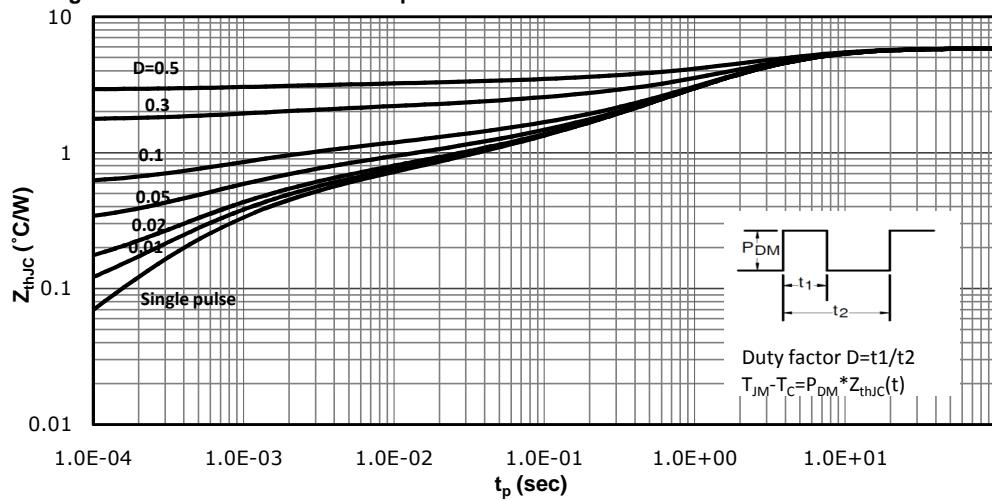
### Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	$V_{SD}$	0.6	0.85	1.1	V	$V_{GS}=0V, I_{SD}=5.5A$
Body Diode Reverse Recovery Time	$t_{rr}$	-	240	-	ns	$I_{sd}=5.5A$ $dI/dt=100A/\mu s$ , $V_{ds}=400V$
Body Diode Reverse Recovery Charge	$Q_{rr}$	-	2.43	-	$\mu C$	

## Typical Performance Characteristics

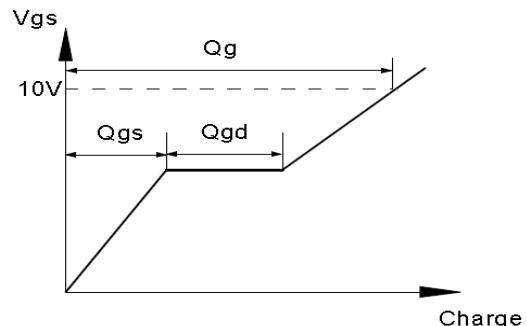
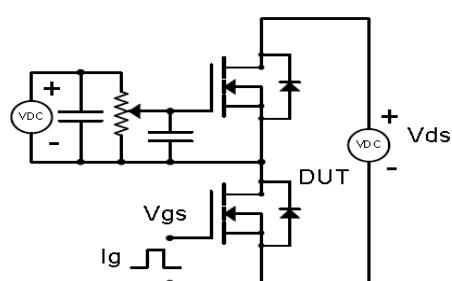
**Fig 1. Output Characteristics ( $T_j=25^\circ\text{C}$ )**

**Fig 2. Output Characteristics ( $T_j=150^\circ\text{C}$ )**

**Fig 3: Transfer Characteristics**

**Fig 4:  $V_{TH}$  Vs  $T_j$  Temperature Characteristics**

**Fig 5:  $R_{DS(on)}$  Vs  $I_D$  Characteristics( $T_c=25^\circ\text{C}$ )**

**Fig 6:  $R_{DS(on)}$  vs. Temperature**


**Fig 7: BV<sub>DSS</sub> vs. Temperature**

**Fig 8: R<sub>d(on)</sub> vs Gate Voltage**

**Fig 9: Body-diode Forward Characteristics**

**Fig 10: Gate Charge Characteristics**

**Fig 11: Capacitance Characteristics**

**Fig 12: Safe Operating Area**


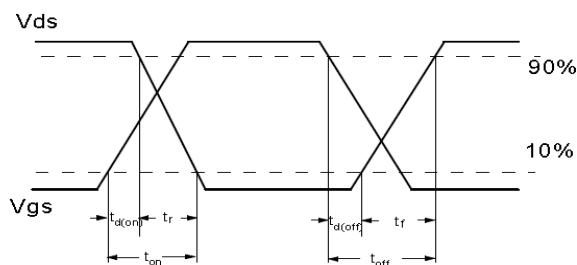
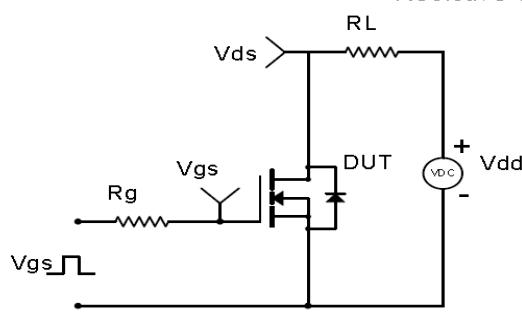
**Fig 13: Max. Transient Thermal Impedance**

**Test Circuit & Waveform**

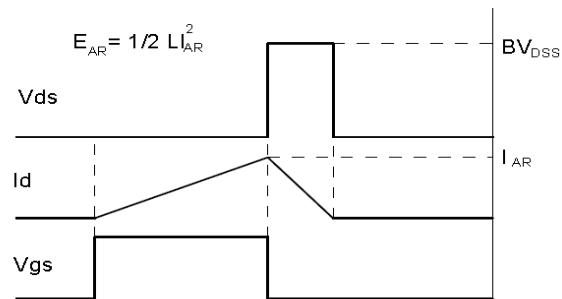
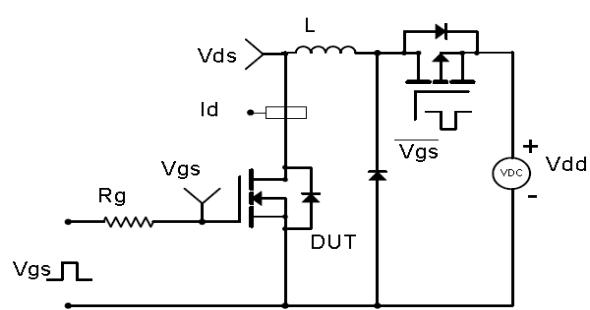
Gate Charge Test Circuit &amp; Waveform



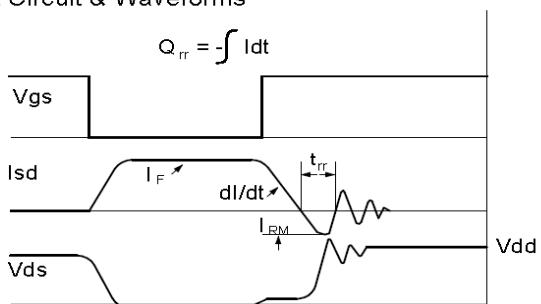
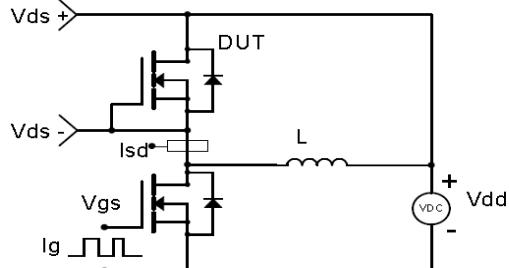
Resistive Switching Test Circuit &amp; Waveforms

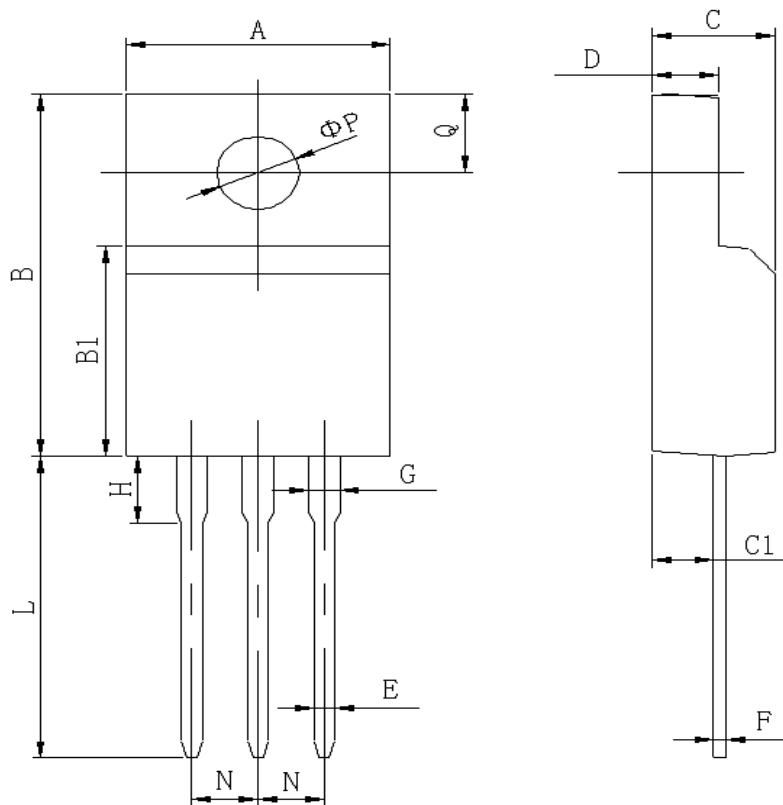


Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms



**Package Outline: TO-220F**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.60	10.40	0.378	0.409
B	15.40	16.20	0.606	0.638
B1	8.90	9.50	0.350	0.374
C	4.30	4.90	0.169	0.193
C1	2.10	3.00	0.083	0.118
D	2.40	3.00	0.094	0.118
E	0.60	1.00	0.024	0.039
F	0.30	0.60	0.012	0.024
G	1.12	1.42	0.044	0.056
H	3.40	3.80	0.134	0.150
L*	12.00	14.00	0.472	0.551
N	2.34	2.74	0.092	0.108
Q	3.15	3.55	0.124	0.140
ΦP	2.90	3.30	0.114	0.130



华润微电子(重庆)有限公司

CRJF380N65G2

SJMOS N-MOSFET 650V, 0.32Ω, 11A

### Revision History

Revison	Date	Major changes
1.0	2021-1-20	Release of first version

### Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.